

## *Change in DiskOnChip FBGA 7x10 Tray*

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### Description

The specifications for tray pocket formation of DiskOnChip G3 512Mb, P3 256Mb, G3 LP 512Mb, P3 LP 256Mb, FBGA 7x10 mm 85 balls will be changed for the products listed in the table below.

### Ordering Information

The following products are affected:

Product	Form Factors	Capacity	Ordering Information
DiskOnChip G3	7x10 FBGA	64MB (512Mbit)	MD4832-d512-V3Q18-X-P MD4832-d512-V3Q18-X
DiskOnChip G3 LP	7x10 FBGA	64MB (512Mbit)	MD6832-d512-V18-X-P MD6832-d512-V18-X
DiskOnChip P3	7x10 FBGA	32MB (256Mbit)	MD5832-d256-V3Q18-X MD5832-d256-V3Q18-X-P
DiskOnChip P3 LP	7x10 FBGA	32MB (256Mbit)	MD7832-d256-V18-X MD7832-d256-V18-X-P

### Reason for Change

The changes will enable the following:

1. Correspond to the future package thickness of 1.0-1.4mm max (instead of the current package thickness of 1.2-1.4mm max).
2. Correspond to the future DiskOnChip G4/P4 ball number of 115 balls (instead of 85 balls).
3. To improve productivity.

### Description of Change

- The pocket height between the upper and lower tray will be changed from 1.9mm to 1.6mm, as shown in Figure 1.

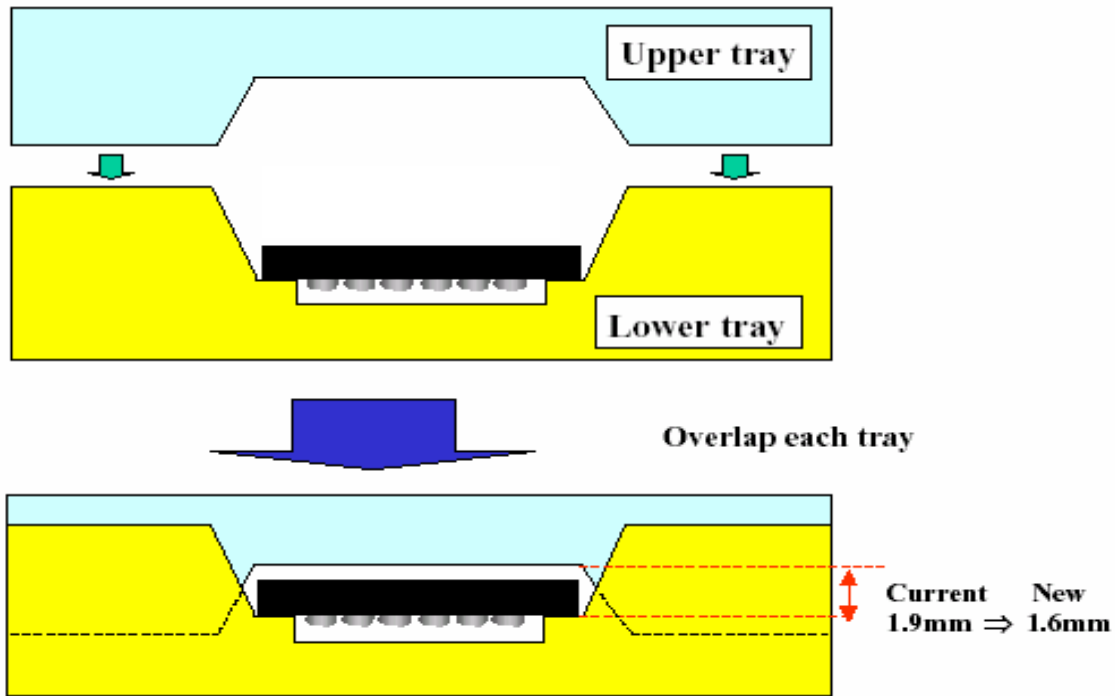


Figure 1: Change of Pocket Height between Upper Lower Trays

- To improve productivity the shape of the tray pocket will be changed to secure the alignment of the package and given extra allowance to the corner of the tray pocket, as in Figure 2

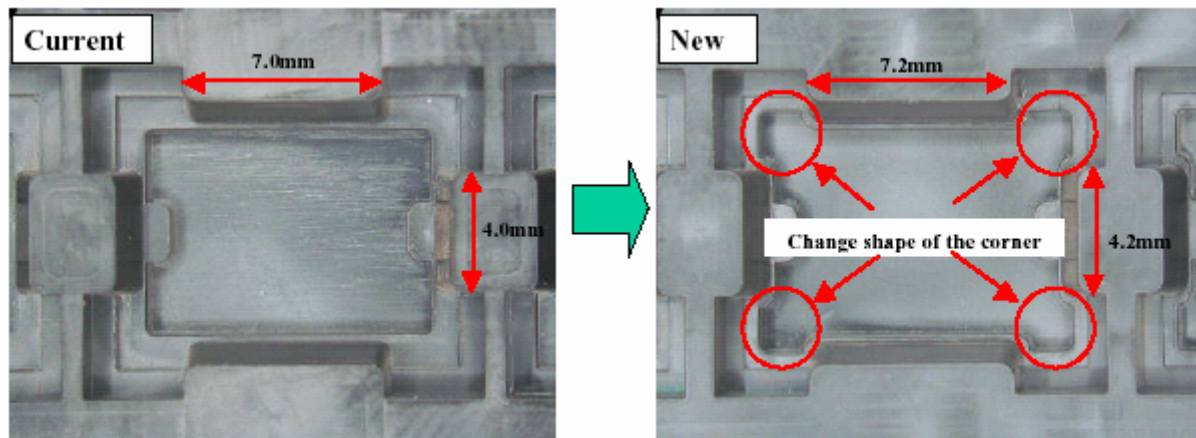


Figure 2: Change in Shape of Tray Pocket

Note:

The number of chips which are loaded in each tray and the pitch between the pockets will not be changed.

**Availability**

DiskOnChip G3/P3, G3/P3 LP FBGA 7x10 will be shipped in the new tray as of May 2005.

**How to Contact Us**

Please contact your M-Systems representative or visit the DiskOnChip web page on the M-Systems website ([www.m-systems.com](http://www.m-systems.com)) for any further information or assistance.

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